

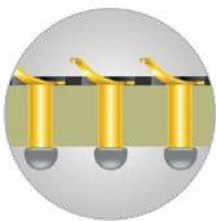
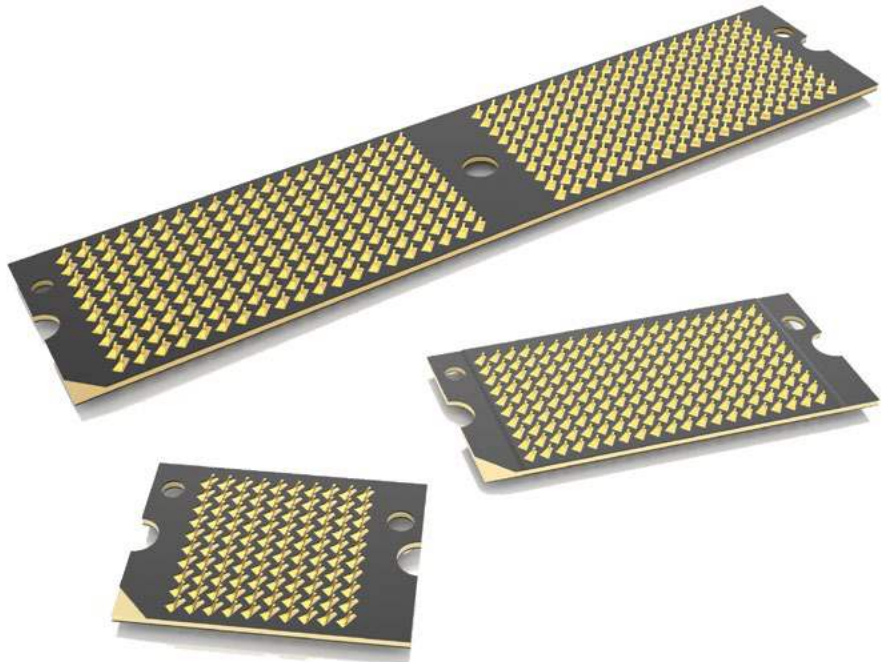


# HIGH-SPEED COMPRESSION INTERPOSER

(0.80 mm) .0315" AND (1.00 mm) .0394" PITCH

## FEATURES & BENEFITS

- Dual compression contacts or single compression with solder balls
- BeCu Micro-formed contacts
- Performance up to 14 Gbps (ZAX Series)
- Low-profile body height for a short signal path
- Highly customizable solutions
- Visit [samtec.com?ZRDP](http://samtec.com?ZRDP) for ultra-low profile Z-Ray® cable assembly



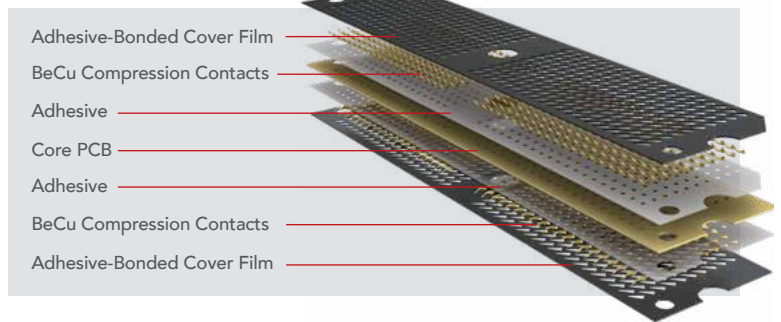
Solder Ball Option



BeCu Compression Contacts

## Design & Construction

- One-piece design assembled into rugged low profile FR4 substrate under high pressure and temperature
- Built standard with a 1 mm board-to-board thickness
- Contacts are designed using BeCu foils that have been formed into the "beam" structure

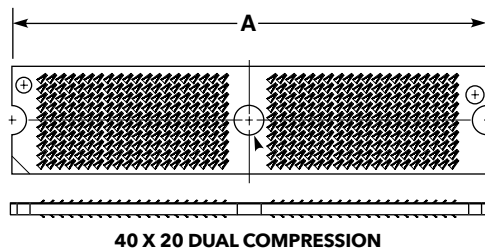
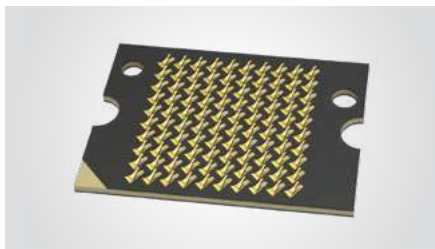


## PERFORMANCE SPECIFICATIONS

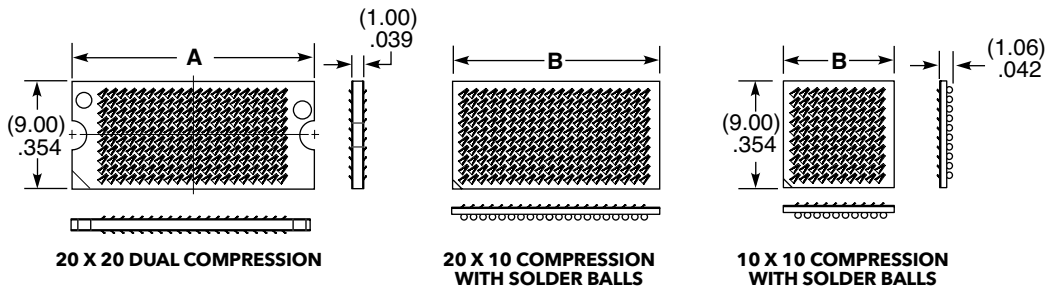
		Single Compression w/ Solder Balls		Dual Compression	
Series		ZA8	ZA1	ZA8	ZA1
Pitch		0.80 mm	1.00 mm	0.80 mm	1.00 mm
Max Row		25	20	50	58
Max Column		25	20	50	58
Thickness	FR4 Core	1.00 to 3 mm	1.00 to 3 mm	0.5 to 3 mm	0.5 to 3 mm
Thickness Tolerance	FR4 Core	±10%	±10%	±10%	±10%
Deflection / Normal Force per Pin		0.20 mm / 30g			
Operating Temperature		-55°C to +105°C (Single Cycle only above 85°C)			

**(0.80 mm) .0315" PITCH • HIGH-SPEED COMPRESSION INTERPOSER**

ZA8	POSITIONS PER ROW	TERMINATION	HEIGHT	PLATING OPTION	NO. OF ROWS	SOLDER TYPE
	-10, -20, -30, -40	-1 = Single Compression with Solder Balls (-10 & -20 positions only)  -2 = Dual Compression (-10, -20, -30 & -40 positions only)	-1.00 = (1.00 mm) .040" Height	-Z = 6 μ" (0.15 μm) Gold in contact area	-10 = Ten Rows	(Termination -1 only)  -1 = Lead  -2 = Lead-Free



POSITIONS PER ROW	A	B
-10	(12.50) .492	(9.35) .368
-20	(20.50) .807	(17.35) .683
-30	(31.70) 1.248	N/A
-40	(39.70) 1.563	N/A



**Notes:**  
Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: [samtec.com?ZA8](http://samtec.com?ZA8)